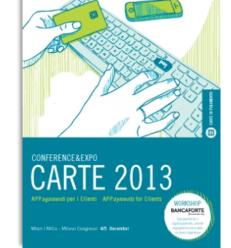


Mobile Payment from Trials to Mass Market

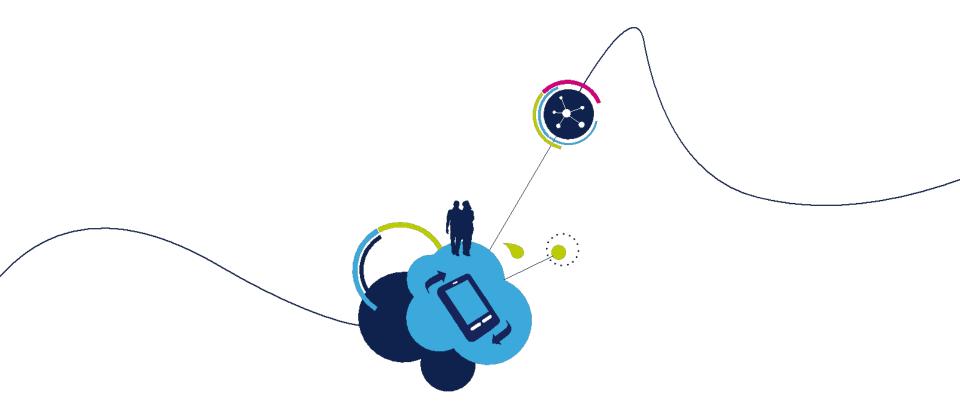
Michele Scarlatella SMD, STMicroelectronics michele.scarlatella@st.com











About STMicroelectronics



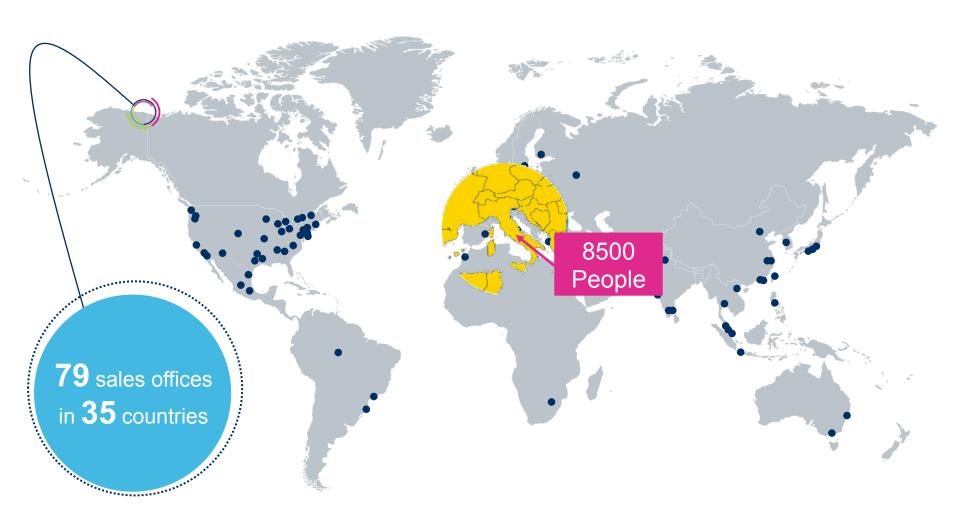


- A global semiconductor leader
- The largest European semiconductor company
- 2012 revenues of **\$8.49B**(1)
- Approx. 48,000 employees worldwide(1)
- Approx. **11,500**⁽¹⁾ people working in R&D
- Approx. \$2.4B in R&D
- 12 manufacturing sites
- Listed on New York Stock Exchange, Euronext Paris and Borsa Italiana, Milano





Partners with our Customers Worldwide





Where you find us 6





Our MEMS & Sensors are augmenting the consumer experience



Our digital consumer products are powering the augmented digital lifestyle



Our automotive products are making driving safer, greener and more entertaining



life.augmented



Our Microcontrollers are everywhere making everything smarter and more secure



Our smart power products are making more of our energy resources

General **Purpose**

Secure MCU



Complete Offer in Security Devices



Secure Mobile Transaction



Classical SIM Advanced SIM M2M SIM



NFC solutions **Secure Elements MIFARETM**

Computer & CE security



Trusted Platform Brand protection



Infrastructure Secure readers **USB** token

Smart Grid



KerKey Secure Element for SmartGrid

Tagging



Product tracking Supply chain mgnt **NFC Dynamic tags**

Personal security





e - ID **Banking Transport Conditional access** Physical access Logical access



Fully Integrated Plant



- Business unit of SMD(*)
- **Market Segments:**
 - Mobile (SIM, NFC-SIM, M2M-SIM, SE)
 - Payment Cards
 - PKI, eID, eGovt
- Fully integrated :
 - Secure OS design, certifications
 - Production Engineering
 - Cards Production
 - Data Preparation
 - Personalization
 - Fulfillment and mailing



Certifications:



























Segmenti di Mercato



Mobile Communications



Banking



Identification and Security









NFC Technology .

- Contactless communication from a Mobile Phone
 - Antenna inside the device
- Secure Element applications based on
 - A SIM Card
 - Embedded Secure Element

- 3 Operating modes
 - The phone is a Card
 - Phone can emulate multiple cards
 - The Phone is a Reader
 - Phone can read RFID tags (NFC Type V), triggering web page, application execution, etc.
 - The Phone can act as a Card reader (mPOS)
 - Peer-to-peer 2 Phones exchanging data
 - Object information exchange

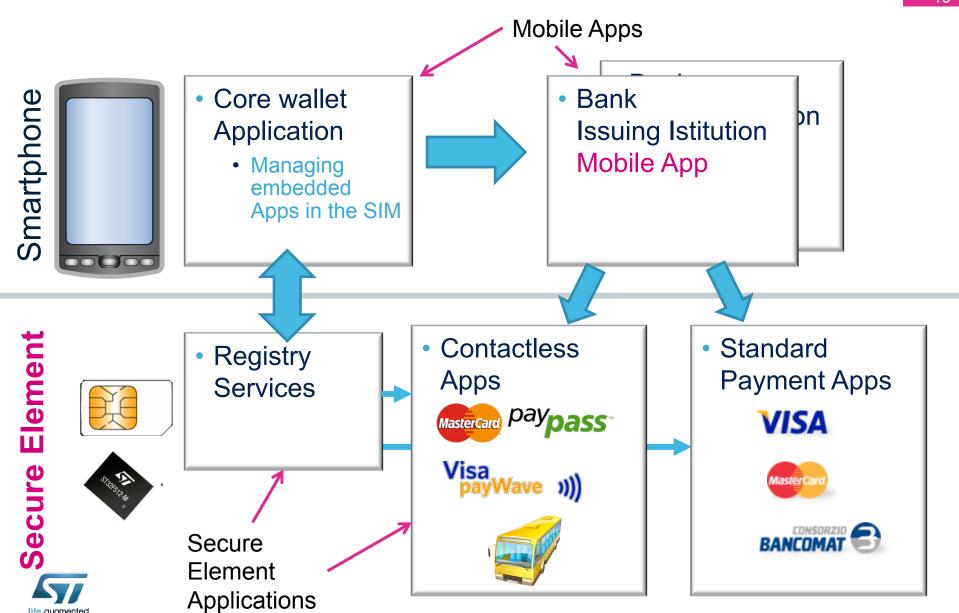


Multiple Capability of Mobile 12





Wallets & Secure Element



Managing the SE – Mobile Applets





- The Mobile Wallet is an application to:
 - Activate/deactivate "virtual card" (Mobile Applets)
 - Select Default Application
 - Access via Mobile Open API (SIMalliance MOAPI V2.04, Test Specification V. 0.9)
 - Subject to Branding Requirement
 - Certifications

Managing the Applets Over-The-Air

- Trusted Service Manager
 - Interconnect MNO with Service provider (Issuer)
 - End-to-end Security
 - Grant Access Rights to Service Providers
 - Application life-cycle management
 - Security Domain management on SE
 - Download/personalize/Activate/Deactivate
 - User Interface
- Multi-Application Repository in the Secure Element





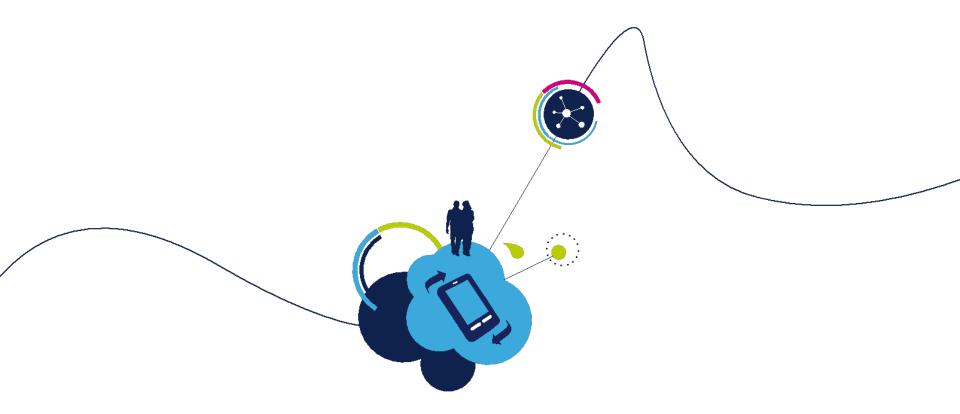










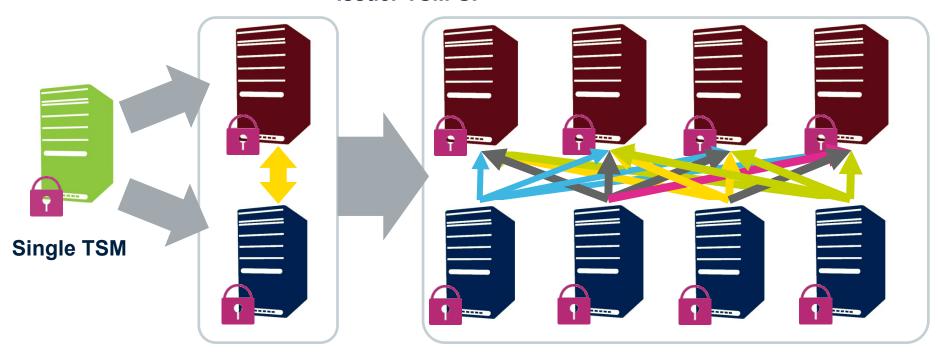


Facing Reality



Multi-operator / Multi-issuer Scenario

Issuer TSM-SP



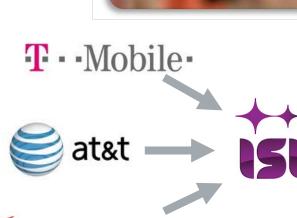
TSM-MNO

- Other Consideration
 - Common/Compatible SE Structure
 - Payments Apps: Which versions?
 - SLA among TSM's



The US Approach

- Joint Venture among main MNO (AT&T, Verizon Wireless, T-Mobile)
 - Common/Compatible SE Structure
 - Pre-defined set of Payment Applications and their Versions:
 - VISA, MasterCard, Amex, Discover
 - Common set of Specifications (isis v.2.0)
 & Specifications roadmap
 - Certifications Roadmap
 - · Isis certification to test compatibility
 - Unique Mobile Wallet
 - Unique TSM
 - Open TSM Architecture
- Common Marketing Plan
 - Marketing and advertisement
 - Nationwide launch: Nov.14th
 - Isis Alliance Program





Marketing







The New Zealand Approach

- Joint Venture among main stakeholders:
 - MNO (Vodafone NZ, Telecom NZ)
 - Issuers (BNZ, ..)
 - Processor (Paymark)
 - Common set of Specifications & features roadmap
 - Certification to test compatibility
 - Pre-defined set of Payment Applications and their Versions
 - Unique Mobile Wallet
- Common Marketing Plan
 - Payment & non-payment applications
 - Nationwide launch Q1 2014 (forecast)





http://www.nfcworld.com/tag/tsm-nz/

New Zealand NFC wallet to launch in 2014



By Karl Dyer ■ • 11 September 2013, 12:48

The new CEO of TSM NZ, the NFC joint venture formed by Paymark, Telecom New Zealand, Vodafone and 2degrees in 2012, has announced that its mobile wallet will be available to the New Zealand market in the second half of 2014

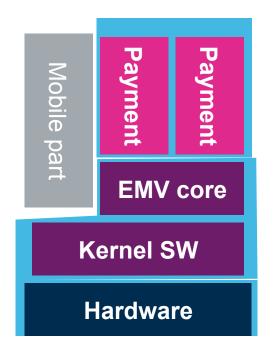
"There has been a lot of anticipation about the arrival of our wallet and unquestionably it will be a game changer," says new head Rob Ellis. "This is going to touch the lives of every New Zealander and we have to get it right.





Mobile Certification Approach

- Three level Certification:
 - Chip Level: Integrated Circuit Card Number
 - EMV Core part: Platform Certificate Number
 - Payment Specific Platform
- ICCN Integrated Circuit Number
 - Valid 1 year
 - Can be renewed 1 yr several times
 - Total validity of ICCN 6yrs max
- PCN Platform Certificate number
 - Must have a valid ICCN to start PCN Certification.
 - The ICCN must be no older than 1 year for new issuance and renewals
 - Can be renewed 1 yr, several times, for a total of 6yr max
- Payment Specific Certifications
 - Depend on Payment Scheme,
 - Typical: 3yr + (1+1+1 year)





The NFC Certification Timeline 6 years **ICCN PCN** Chip Payment 1 **Develop** Payment 2 ement **Card OS Developement MNO** Acceptance Tests & **Trials Mass Market**

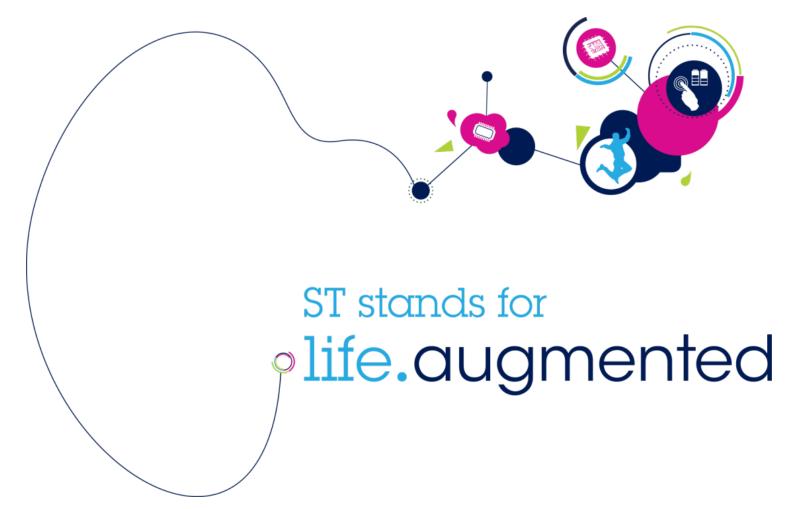
Useful life-time: 2-3years

Summary and Take Away



- Move to Mobile Payment Seem an unstoppable trend posed to change Electronic Landscape forever
- NFC Complexity must be managed.
 Nation-wide initiative, alliance are a way to solve complexity
 - Not unique solutions exists
- Services and solutions must not a burden onto the user





Contact:

Michele Scarlatella

michele.scarlatella@st.com SMD Division, STMicroelectronics www.st.com

